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## **PACKAGED ELECTRONIC COMPONENT FOR APPLICATIONS AT MILLIMETRIC FREQUENCIES**

### **CROSS - REFERENCE TO RELATED APPLICATIONS**

The present Application is based on International Application No. PCT/EP2003/050846, filed on November 18, 2003, which in turn corresponds to FR 02/14684 filed on November 22, 2002, and priority is hereby claimed under 35 USC §119 based on these applications. Each of these applications are hereby incorporated by reference in their entirety into the present application.

### **FIELD OF THE INVENTION**

The invention relates to electronic circuits working at very high frequencies, greater than 45 GHz, also called "millimetric frequencies".

### **BACKGROUND OF THE INVENTION**

These electronic circuits are used for radar type applications in which an electromagnetic wave is sent at a millimetric frequency and a wave reflected by an obstacle is received by an antenna, to extract from this wave, on the one hand, distance information and, on the other hand, relative speed information, between this obstacle and the source that sent the wave.

The millimetric frequency circuits can also be used for short distance and very high bit rate communication applications.

Whatever the application, the electronic processing of the millimetric frequency signals comprises a low frequency processing part that can be implemented by silicon integrated circuits mounted on printed circuits. This part can be produced by very commonly used and inexpensive technologies, with connections that are simple to produce between circuit elements on one and the same integrated circuit chip or between different integrated circuit chips. The processing also comprises a